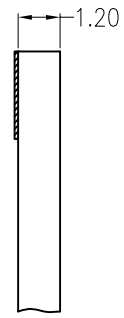
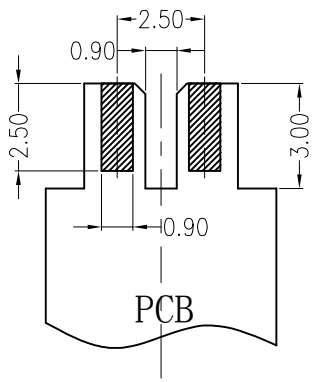
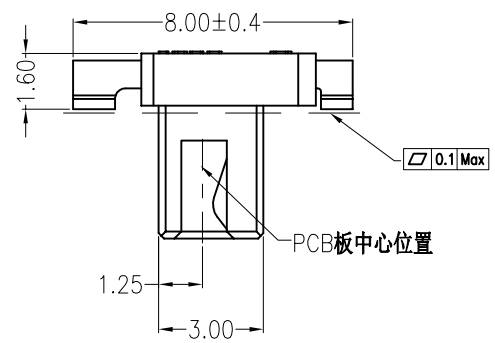
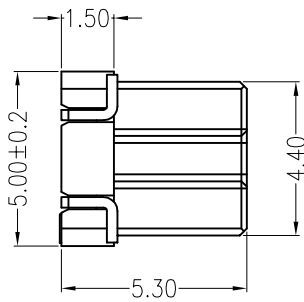
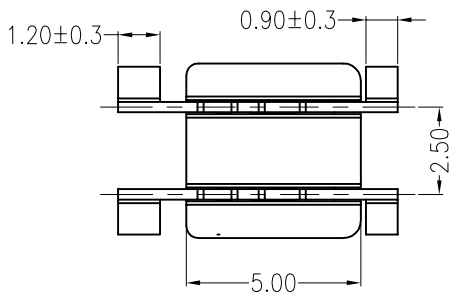


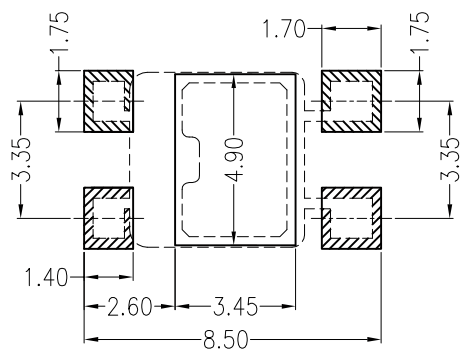
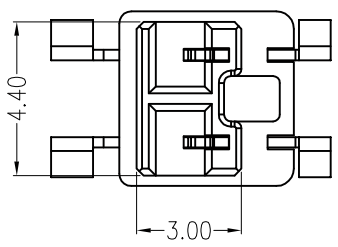
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	李润	2014.04.16



Mating PCB detail

主要技术参数 Main Specifications

板厚 (thickness): 1.2mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
 额定电压 (Rated voltage): 125V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐电压 (Withstand Voltage): 800V AC/minute
 温度范围 (Temperature Range): $-40^{\circ}C \sim +105^{\circ}C$



Board Layout

C				
B	CONTACT	2 PCS	PhosphorBronze	Tin-plated
A	HOUSING	1 PCS	PA9T	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
LEDsconn				TITLE: 2.5Pitch 180°wafer smt type
X.±0.5	X.±5'	USE: CUSTOMER		PART NO.:
.X±0.3	.X±2'	APPD: 邵敬和		DWG NO.:
.XX±0.25	.XX±1'	CHKD: 田峰		
--	--	DR: 吴丹平		SCALE 1 : 1
UNITS: mm				SHEET 1 / 1